



# **IPC/PERM-2901**

## **2018 - February**

### **Pb-free Design & Assembly Implementation Guide**

*An international standard developed by IPC*

*Association Connecting Electronics Industries*



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- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Developed by the Research Coordination and Technical Guidance Task Group (8-81D) of the PERM Council (8-80) of IPC

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